



规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_

PRODUCT 产品: \_\_\_\_\_ SAW RESONATOR \_\_\_\_\_

MODEL NO 型号: \_\_\_\_\_ R315M T039 \_\_\_\_\_

PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_

APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2011-6-20 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

深圳市春宇无线有限公司  
CY Wireless Technology Limited



更改历史记录  
History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark



### 1. SCOPE

This specification is applied to a SAW resonator designed for the stabilization of transmitters such as garage door openers and security transmitters.

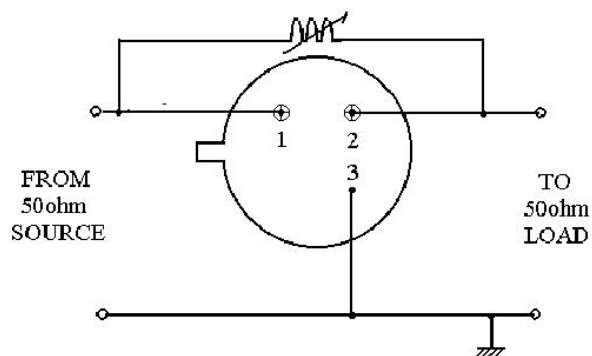
### 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

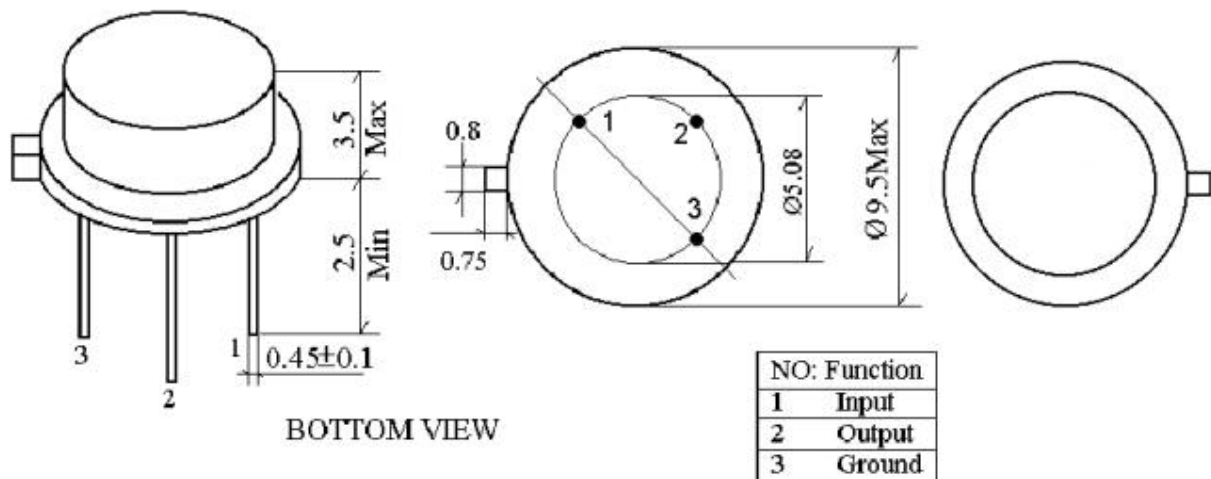
#### 2.2 Electronic Characteristics

Item	Unites	Minimum	Typical	Maximum	
Center Frequency	MHz	314.925	315.000	315.075	
Insertion Loss	dB		1.5	2.2	
Quality Factor Unload Q		8000	12800		
50 Ω Loaded Q		1000	2000		
Temperature	Turnover Temperature	°C	10	25	40
Stability	Freq.temp.Coefficient	ppm/°C <sup>2</sup>		0.037	
Frequency Aging		ppm/yr		≤10	
DC. Insulation Resistance	MΩ	1.0			
RF Equivalent RLC Model	Motional Resistance R1	Ω		16	26
	Motional Inductance L1	μ H		107.29	
	Motional Capacitance C1	fF		2.3797	
Transducer Static Capacitance	pF		2.47		

### 3. TEST CIRCUIT



#### 4. DIMENSION



#### 5. ENVIRONMENTAL CHARACTERISTICS

##### 5-1 High temperature exposure

Subject the device to  $+85^\circ\text{C}$  for 16 hours. Then release the resonator into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

##### 5-2 Low temperature exposure

Subject the device to  $-40^\circ\text{C}$  for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

##### 5-3 Temperature cycling

Subject the device to a low temperature of  $-40^\circ\text{C}$  for 30 minutes. Following by a high temperature of  $+85^\circ\text{C}$  for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

##### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at  $260^\circ\text{C} \pm 10^\circ\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

##### 5-5 Solderability

Subject the device terminals into the solder bath at  $245^\circ\text{C} \pm 5^\circ\text{C}$  for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

##### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

**5-7 Vibration**

Subject the device to the vibration for 1 hour each in x, y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

**6. REMARK****6.1 Static voltage**

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

**6.2 Ultrasonic cleaning**

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

**6.3 Soldering**

Only leads of component may be soldered. Please avoid soldering another part of component.